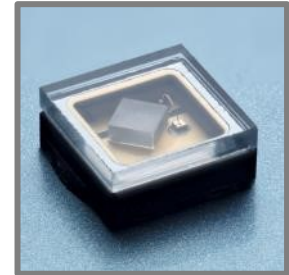


High power UV LED Chip in SMD Flat-top Package

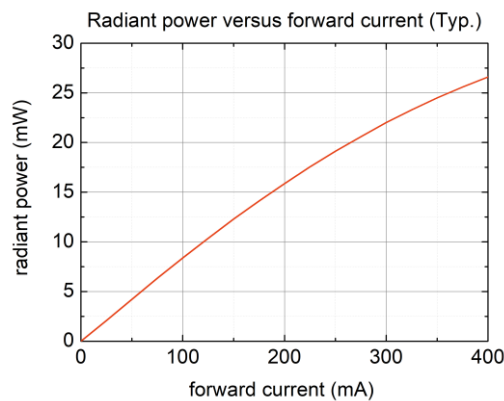
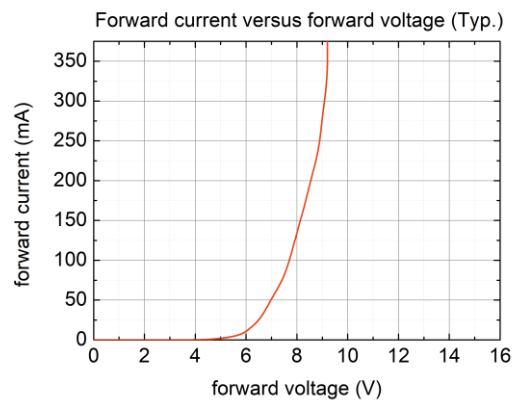
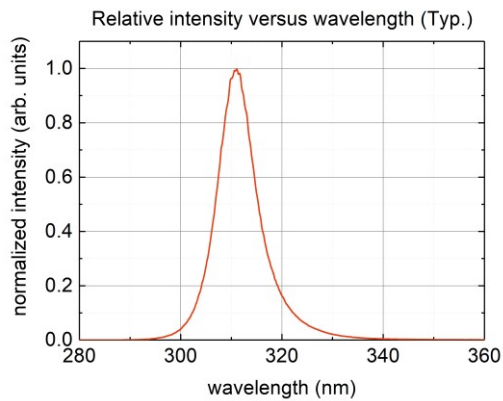
Wavelengths: 310 nm

Optical and electrical characteristics



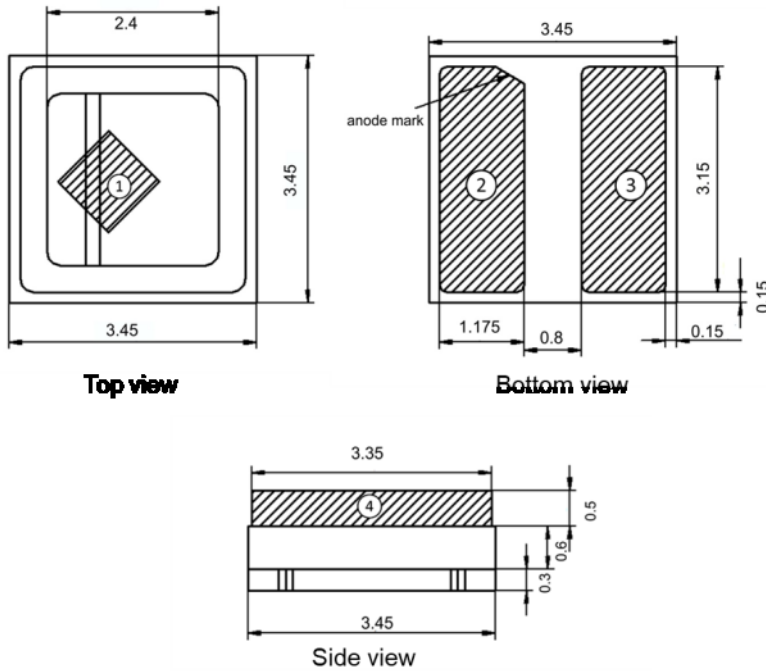
($I_F = 350 \text{ mA}$, $T_{amb} = 20^\circ\text{C}$)

Parameter	Unit	HP310SMD		
		Min.	Typ.	Max.
Peak wavelength	nm	305	310	315
Full width at half maximum	nm	7	7.5	9
Forward voltage	V	7	8.5	10
Radiant power	mW	20	25	30



Mechanical dimensions

(All dimensions in mm)



No.	Part name	Material
1	LED chip	AlGaIn/ sapphire
2	anode	Au
3	cathode	Au
4	sealing glass	quartz

Note:

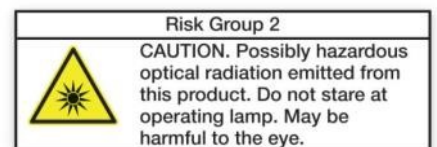
LED chips designed for flip-chip bonding i.e. light is extracted through the transparent substrate.

Customization:

- Wavelength customization between 230 nm and 330 nm on request.
- SMD and TO-39 packages can be developed on request.

Handling precautions:

- LEDs are sensitive to static electricity.
- Use of ESD protection during handling is strongly recommended.



More information at www.uvphotonics.de or contact us at info@uvphotonics.de.